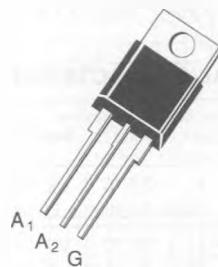


SNUBBERLESS TRIACS

- $I_{TRMS} = 10 \text{ A}$ at $T_c = 90^\circ\text{C}$.
- V_{DRM} : 200 V to 800 V.
- $I_{GT} = 35 \text{ mA}$ (QI-II-III).
- GLASS PASSIVATED CHIP.
- HIGH SURGE CURRENT : $I_{TSM} = 100 \text{ A}$.
- HIGH COMMUTATION CAPABILITY :
 $(di/dt)_c > 5.5 \text{ A / ms}$ without snubber.
- INSULATING VOLTAGE : 2500 V_{RMS}.
- UL RECOGNIZED (E81734).


TO 220 AB
 (CB-415 Plastic)

DESCRIPTION

New range suited for applications such as phase control and static switching on inductive or resistive load.

ABSOLUTE RATINGS (limiting values)

| Symbol | Parameter | Value | | Unit |
|--------------------|--|-----------------------------------|-----|--------------------------|
| I_{TRMS} | RMS on-state current (360 ° conduction angle) | $T_c = 90^\circ\text{C}$ | 10 | A |
| I_{TSM} | Non repetitive surge peak on-state current (T_j initial = 25 °C) | $t = 8.3 \text{ ms}$ | 105 | A |
| | | $t = 10 \text{ ms}$ | 100 | |
| $I^2 t$ | $I^2 t$ value | $t = 10 \text{ ms}$ | 50 | $\text{A}^2 \text{ s}$ |
| di/dt | Critical rate of rise of on-state current (1) | Repetitive $F = 50 \text{ Hz}$ | 20 | $\text{A} / \mu\text{s}$ |
| | | Non Repetitive | 100 | |
| T_{sig} T_j | Storage and operating junction temperature range | -40, +150 -40, +125 | | °C |

| Symbol | Parameter | BTA 10- | | | | | Unit |
|-----------|---------------------------------------|---------|--------|--------|--------|--------|------|
| | | 200 CW | 400 CW | 600 CW | 700 CW | 800 CW | |
| V_{DRM} | Repetitive peak off-state voltage (2) | ± 200 | ± 400 | ± 600 | ± 700 | ± 800 | V |

(1) Gate supply : $I_G = 350 \text{ mA}$ - $dI_G / dt = 1 \text{ A / } \mu\text{s}$.

(2) $T_j = 125^\circ\text{C}$.

THERMAL RESISTANCES

| Symbol | Parameter | Value | Unit |
|----------------------------|---|-------|------|
| R _{th} (j - a) | Junction to ambient | 60 | °C/W |
| R _{th} (j - c) DC | Junction to case for DC | 3.3 | °C/W |
| R _{th} (j - c) AC | Junction to case for 360 ° conduction angle (F = 50 Hz) | 2.5 | °C/W |

GATE CHARACTERISTICS (maximum values)

P_{GM} = 40 W (t = 10 µs) P_{G (AV)} = 1 W I_{GM} = 4 A (t = 10 µs) V_{GM} = 16 V (t = 10 µs).

ELECTRICAL CHARACTERISTICS

| Symbol | Test Conditions | | | Quadrants | Min. | Typ. | Max. | Unit |
|------------------------|--|-----------------------------------|-------------------------|-----------|------|------|------|------|
| I _{GT} | T _j = 25 °C | V _D = 12 V | R _L = 33 Ω | I-II-III | 1 | | 35 | mA |
| | Pulse duration > 20 µs | | | | | | | |
| V _{GT} | T _j = 25 °C | V _D = 12 V | R _L = 33 Ω | I-II-III | | | 1.5 | V |
| | Pulse duration > 20 µs | | | | | | | |
| V _{GD} | T _j = 125 °C | V _D = V _{DRM} | R _L = 3.3 kΩ | I-II-III | 0.2 | | | V |
| | Pulse duration > 20 µs | | | | | | | |
| I _H * | T _j = 25 °C | I _T = 100 mA | | | | | 35 | mA |
| | Gate open | R _L = 140 Ω | | | | | | |
| I _G | T _j = 25 °C | V _D = 12 V | I _G = 350 mA | I-III | | | 50 | mA |
| | Pulse duration > 20 µs | | | II | | | 80 | |
| V _{TM} * | T _j = 25 °C | I _{TM} = 14 A | t _p = 10 ms | I | | | 1.65 | V |
| I _{DRM} * | T _j = 25 °C | V _{DRM} rated | Gate open | | | | 0.01 | mA |
| | T _j = 125 °C | | | | | | 2 | |
| dv/dt * | T _j = 125 °C | Gate open | | | 250 | 500 | | V/µs |
| | Linear slope up to 0.67 V _{DRM} | | | | | | | |
| (di/dt) _c * | T _j = 125 °C | V _{DRM} rated | | | 5.5 | 11 | | A/ms |
| | Without snubber | | | | | | | |
| t _{g1} | T _j = 25 °C | di _G /dt = 1 A/µs | I _G = 350 mA | I-II-III | | 2 | | µs |
| | I _T = 14 A | V _D = V _{DRM} | | | | | | |

* For either polarity of electrode A₂ voltage with reference to electrode A₁.

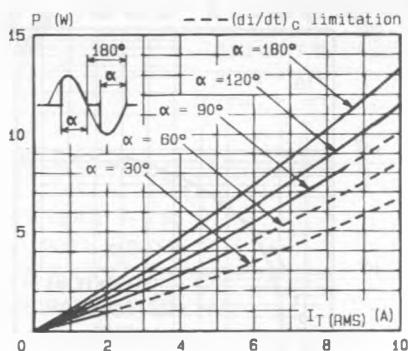


Fig.1 - Maximum mean power dissipation versus RMS on-state current ($f = 60$ Hz).

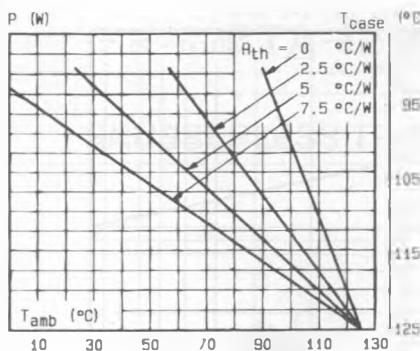


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

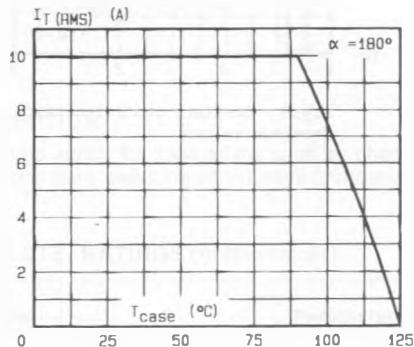


Fig.3 - RMS on-state current versus case temperature.

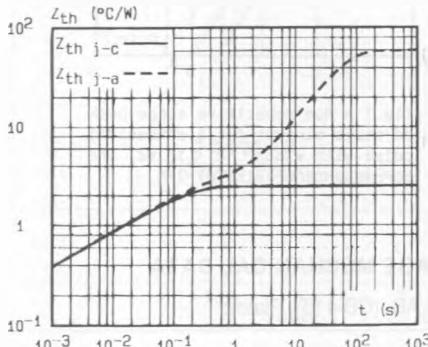


Fig.4 Thermal transient impedance junction to case and junction to ambient versus pulse duration.

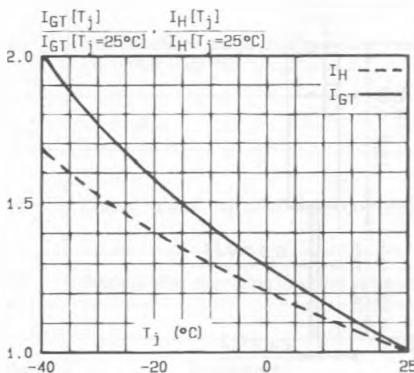


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

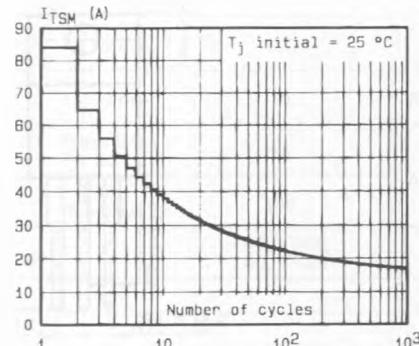


Fig.6 Non repetitive surge peak on state current versus number of cycles.

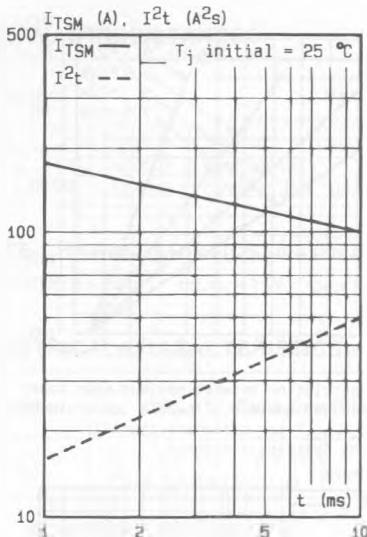


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms. and corresponding value of I^2t .

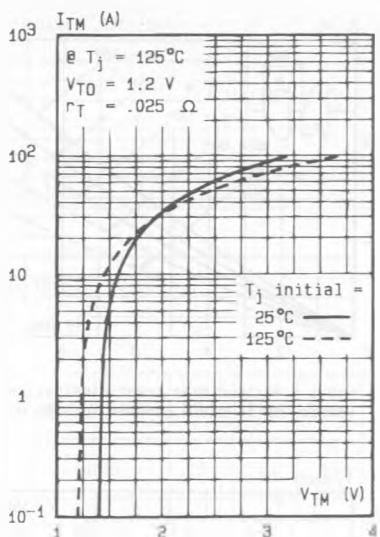
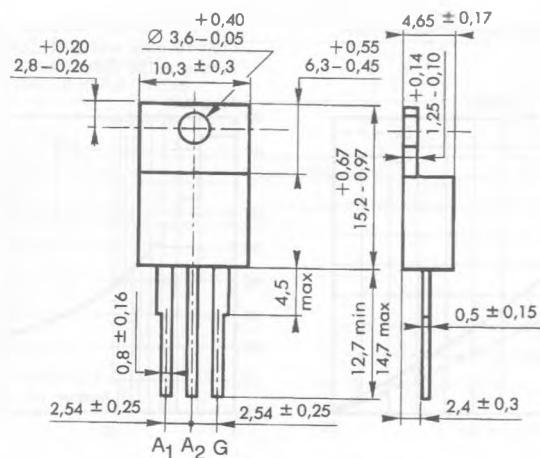


Fig.8 - On-state characteristics
(maximum values).

PACKAGE MECHANICAL DATA

TO 220 AB (CB-415) Plastic



Cooling method : by conduction (method C)

Marking : type number

Weight : 2 g